Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	8
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	82.0	5.69 E-03	364864
Resin	15.0	1.04 E-03	66662
Sb2O3	1.4	9.70 E-05	6222
Brominated epoxy	1.0	6.93 E-05	4444
Carbon Black	0.6	3.47 E-05	2222
Subtotal		6.93 E-03	444414

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.95 E-03	445984
Fe	2.35	1.62 E-04	10417
Zn	0.12	9.00 E-06	577
P	0.03	1.73 E-06	111
Subtotal		7.13 E-03	457088

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	7.20 E-05	4617

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	5.24 E-04	33600

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.70 E-04	10901

Chip

	% of Chip	Weight (g)	PPM
Si	100	7.00 E-04	44890

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	5.60 E-05	3591
Resin	15	1.05 E-05	673
Aromatic Amine	5	3.50 E-06	224
Subtotal		7.00 E-05	4489

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES
Cd	Not Detected	Draft IEC 62321. ICP-OES
Hg	Not Detected	Draft IEC 62321. ICP-OES
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES
Cd	Not Detected	Draft IEC 62321. ICP-OES
Hg	Not Detected	Draft IEC 62321. ICP-OES
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
1.56 E-02	1000000

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ADI Proprietary

Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	8
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	82.0	5.69 E-03	364022
Resin	15.0	1.04 E-03	66508
Sb2O3	1.4	9.70 E-05	6207
Brominated epoxy	1.0	6.93 E-05	4434
Carbon Black	0.6	3.47 E-05	2217
Subtotal		6.93 E-03	443389

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.95 E-03	444955
Fe	2.35	1.62 E-04	10393
Zn	0.12	9.00 E-06	576
P	0.03	1.73 E-06	111
Subtotal		7.13 E-03	456034

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	7.20 E-05	4607

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.76 E-04	30455
Pb	15	8.40 E-05	5374
Subtotal		5.60 E-04	35829

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.70 E-04	10876

Chip

	% of Chip	Weight (g)	PPM
Si	100	7.00 E-04	44787

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	5.60 E-05	3583
Resin	15	1.05 E-05	672
Aromatic Amine	5	3.50 E-06	224
Subtotal		7.00 E-05	4479

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES
Cd	Not Detected	Draft IEC 62321. ICP-OES
Hg	Not Detected	Draft IEC 62321. ICP-OES
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES
Cd	Not Detected	Draft IEC 62321. ICP-OES
Hg	Not Detected	Draft IEC 62321. ICP-OES
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
1.56 E-02	1000000

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ADI Proprietary

Materials Declaration

Package	SOT23-COL
Body Size	
LeadCount	8
Option	NiPdAu

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	80.8	5.60 E-03	364316
Epoxy resin	9.0	6.24 E-04	40580
Phenol Resin	5.0	3.47 E-04	22544
Metal Hyroxide	5.0	3.47 E-04	22544
Carbon Black	0.2	1.39 E-05	902
Subtotal	100.0	6.93 E-03	450886

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	6.93 E-03	450949
Iron	2.35	1.67 E-04	10869
Zinc	0.12	8.53 E-06	555
Phosphorus	0.03	2.13 E-06	139
Subtotal	100	7.11 E-03	462512

Internal/External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Nickel	90.91	8.28 E-05	5387
Palladium	7.91	7.20 E-06	468
Gold	1.19	1.08 E-06	70
Subtotal	100.00	9.11 E-05	5926

Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	1.70 E-04	11060

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	1.00 E-03	65063

Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	2.17 E-05	1412
Metal Oxide	31	2.17 E-05	1412
Glycol Ethers	22	1.54 E-05	1002
Silica	8	5.60 E-06	364
Curing agent & hardener	8	5.60 E-06	364
Subtotal	100	7.00 E-05	4554

Molding Compound

Substance	PPM	Method
Lead	Not Detected	Draft IEC62321. ICP-OES.
Cadmium	Not Detected	Draft IEC62321. ICP-OES.
Mercury	Not Detected	Draft IEC62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC62321. GC-MSD.

Die Attach Paste

Substance	PPM	Method
Lead	Not Detected	Draft IEC62321. ICP-OES.
Cadmium	Not Detected	Draft IEC62321. ICP-OES.
Mercury	Not Detected	Draft IEC62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC62321. GC-MSD.

Package Totals

Weight (g)	PPM
1.54 E-02	1000000

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ADI Proprietary

Materials Declaration

Package	SOT 23 - FCOL
Body Size	--
LeadCount	8
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	82.1	6.78 E-03	383994
Resin	15.0	1.24 E-03	70157
Sb2O3	1.4	1.16 E-04	6548
Brominated epoxy	1.0	8.26 E-05	4677
Carbon Black	0.5	4.13 E-05	2339

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.57	5.42 E-03	306839
Fe	2.28	1.27 E-04	7166
P	0.02	1.35 E-06	76
Zn	0.13	7.01 E-06	397

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	5.61 E-05	3177

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	5.52 E-04	31253

Solder Paste

Item	% of Solder Paste	Weight (g)	PPM
Pb	75.0	4.20 E-04	23782
In	25.0	1.40 E-04	7927

Wafer Bumps

	% of Wafer Bumps	Weight (g)	PPM
Pb	90.0	2.58 E-04	14609
Sn	10.0	2.90 E-05	1642

UBM

	% of UBM	Weight (g)	PPM
Cu	66.67	1.00 E-06	57
NiV	26.67	4.00 E-07	23
Al	6.67	1.00 E-07	6

Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	2.39 E-03	135331

Molding Compound

Item	PPM	Method
Pb	None Detected	USEPA 3052. ICP-OES
Cd	None Detected	USEPA 3052. ICP-OES
Hg	None Detected	USEPA 3052. ICP-OES
Cr+6	None Detected	USEPA 3060A & 7196A. UV-VIS
PBB	None Detected	Analysis was performed by GC/MS.
PBDE	None Detected	Analysis was performed by GC/MS.

Package Totals

Weight (g)	PPM
1.77 E-02	1000000

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